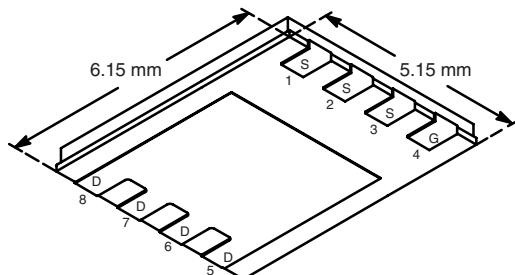


## P-Channel 30-V (D-S) MOSFET

### PRODUCT SUMMARY

$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A) <sup>a</sup>	$Q_g$ (Typ.)
- 30	0.0065 at $V_{GS} = - 10$ V	- 35	100 nC

### PowerPAK SO-8



Bottom View

Ordering Information: Si7447ADP-T1-E3 (Lead (Pb)-free)  
Si7447ADP-T1-GE3 (Lead (Pb)-free and Halogen-free)

### FEATURES

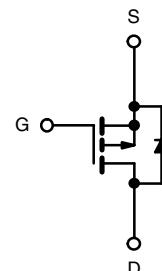
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET
- New Low Thermal Resistance PowerPAK® Package with Low 1.07 mm Profile
- 100 %  $R_g$  Tested



**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**  
Available

### APPLICATIONS

- Battery and Load Switching
  - Notebook Computers
  - Notebook Battery Packs



P-Channel MOSFET

### ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	- 30	V
Gate-Source Voltage	$V_{GS}$	$\pm 25$	
Continuous Drain Current ( $T_J = 150$ °C)	$I_D$	- 35	A
		- 28	
		- 21.5 <sup>b, c</sup>	
		- 17 <sup>b, c</sup>	
Pulsed Drain Current	$I_{DM}$	- 60	A
Continuous Source-Drain Diode Current	$I_S$	- 28	
		- 4.3 <sup>b, c</sup>	
Single Pulse Avalanche Current	$I_{AS}$	40	mJ
Avalanche Energy	$E_{AS}$	80	
Maximum Power Dissipation	$P_D$	83.3	W
		53.3	
		5.4 <sup>b, c</sup>	
		3.4 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) <sup>d, e</sup>		260	

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b, f</sup>	$R_{thJA}$	18	23	°C/W
Maximum Junction-to-Case (Drain)	$R_{thJC}$	1.0	1.3	

Notes:

- a. Based on  $T_C = 25$  °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c.  $t = 10$  s.
- d. See Solder Profile ([www.vishay.com/doc?73257](http://www.vishay.com/doc?73257)). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under Steady State conditions is 65 °C/W.

**SPECIFICATIONS**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

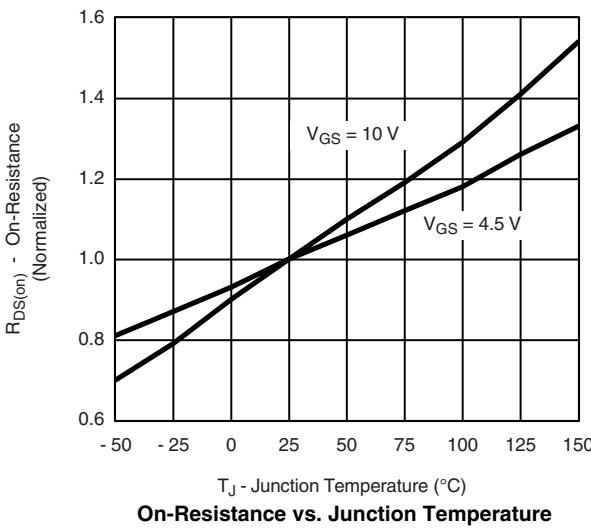
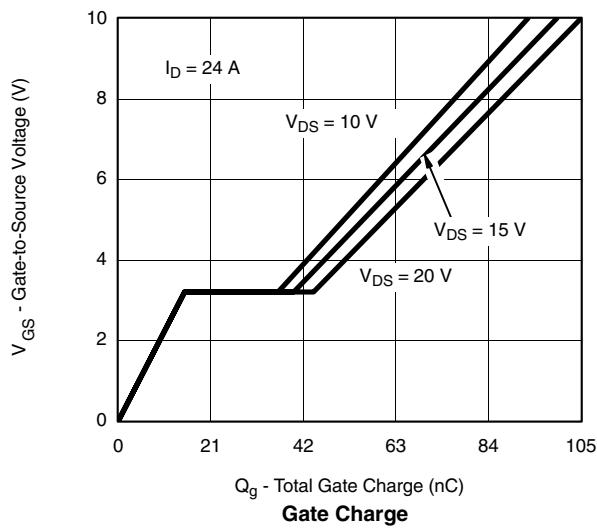
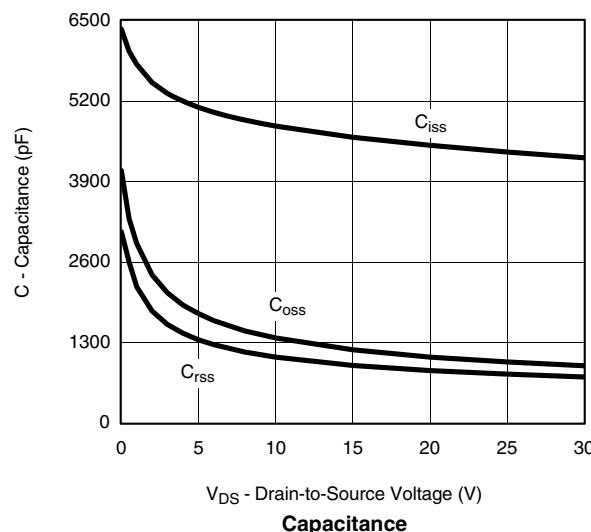
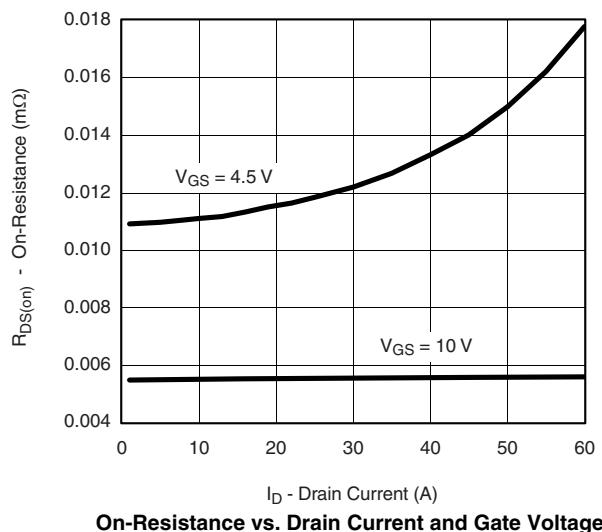
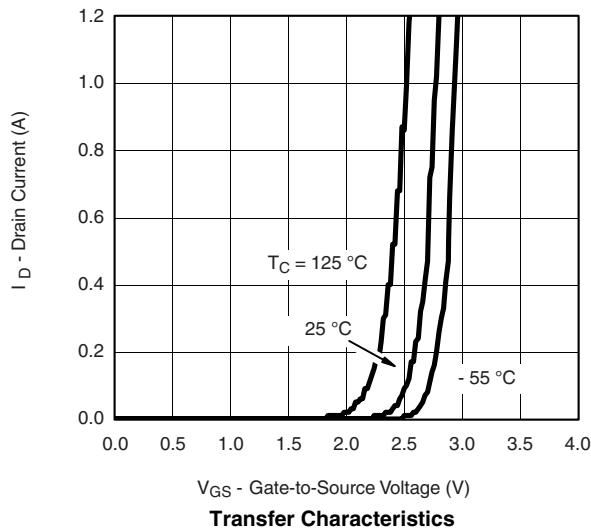
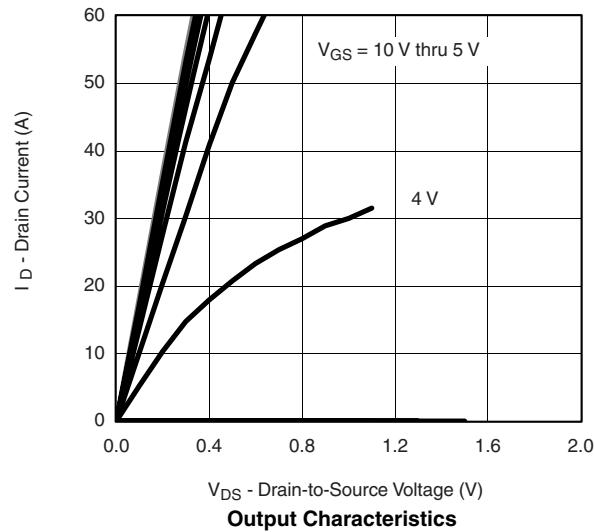
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}$ , $I_D = -250 \mu\text{A}$	- 30			V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250 \mu\text{A}$		- 33		$\text{mV}/^\circ\text{C}$
$V_{GS(\text{th})}$ Temperature Coefficient	$\Delta V_{GS(\text{th})}/T_J$			5.3		
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$ , $I_D = -250 \mu\text{A}$	- 1	- 2.0	- 3	V
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}$ , $V_{GS} = \pm 25 \text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -30 \text{ V}$ , $V_{GS} = 0 \text{ V}$			- 1	$\mu\text{A}$
		$V_{DS} = -30 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 55^\circ\text{C}$			- 10	
On-State Drain Current <sup>a</sup>	$I_{D(\text{on})}$	$V_{DS} \geq -5 \text{ V}$ , $V_{GS} = -10 \text{ V}$	- 30			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(\text{on})}$	$V_{GS} = -10 \text{ V}$ , $I_D = -24 \text{ A}$		0.0054	0.0065	$\Omega$
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -15 \text{ V}$ , $I_D = -24 \text{ A}$		50		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -15 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $f = 1 \text{ MHz}$		4650		$\text{pF}$
Output Capacitance	$C_{oss}$			1200		
Reverse Transfer Capacitance	$C_{rss}$			930		
Total Gate Charge	$Q_g$	$V_{DS} = -15 \text{ V}$ , $V_{GS} = -10 \text{ V}$ , $I_D = -24 \text{ A}$		100	150	$\text{nC}$
Gate-Source Charge	$Q_{gs}$			15.5		
Gate-Drain Charge	$Q_{gd}$			25		
Gate Resistance	$R_g$	$f = 1 \text{ MHz}$	1.7	3.5	5.3	$\Omega$
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = -15 \text{ V}$ , $R_L = 1.5 \Omega$ $I_D \approx -10 \text{ A}$ , $V_{GEN} = -10 \text{ V}$ , $R_g = 1 \Omega$		20	30	$\text{ns}$
Rise Time	$t_r$			25	40	
Turn-Off Delay Time	$t_{d(\text{off})}$			82	125	
Fall Time	$t_f$			98	150	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25^\circ\text{C}$			- 28	$\text{A}$
Pulse Diode Forward Current <sup>a</sup>	$I_{SM}$				- 60	
Body Diode Voltage	$V_{SD}$	$I_S = -4.3 \text{ A}$		- 0.72	- 1.1	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = -19 \text{ A}$ , $dI/dt = -100 \text{ A}/\mu\text{s}$ , $T_J = 25^\circ\text{C}$		47	70	$\text{ns}$
Body Diode Reverse Recovery Charge	$Q_{rr}$			50	75	
Reverse Recovery Fall Time	$t_a$			22		$\text{ns}$
Reverse Recovery Rise Time	$t_b$			25		

Notes:

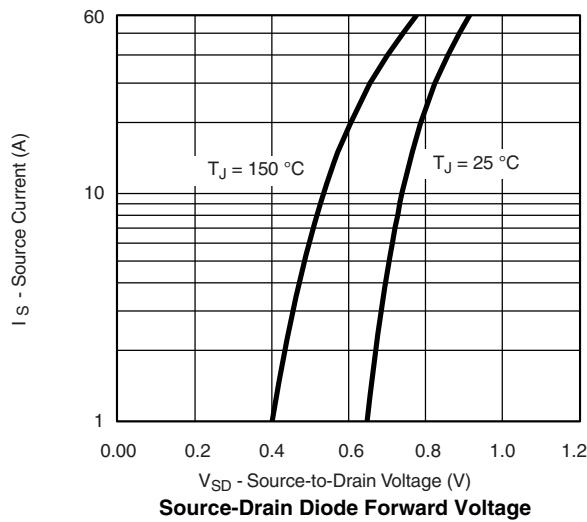
a. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .

b. Guaranteed by design, not subject to production testing.

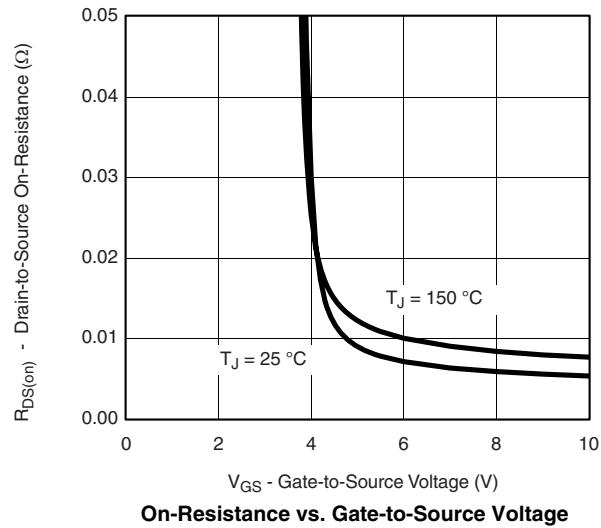
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted


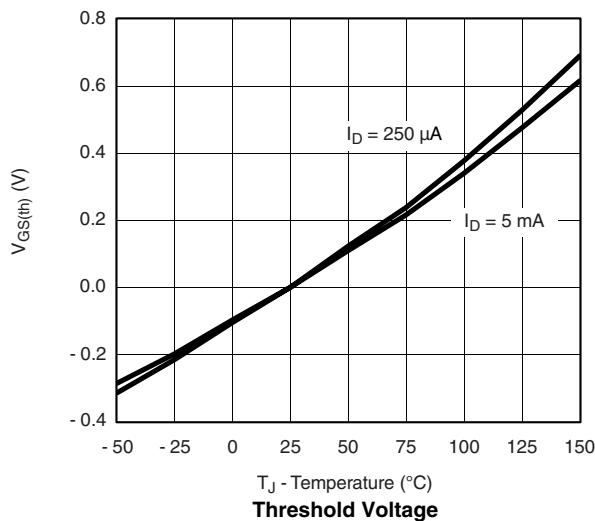
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



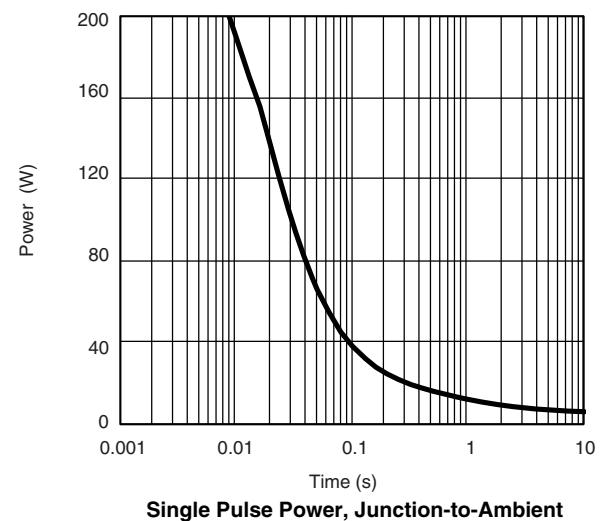
Source-Drain Diode Forward Voltage



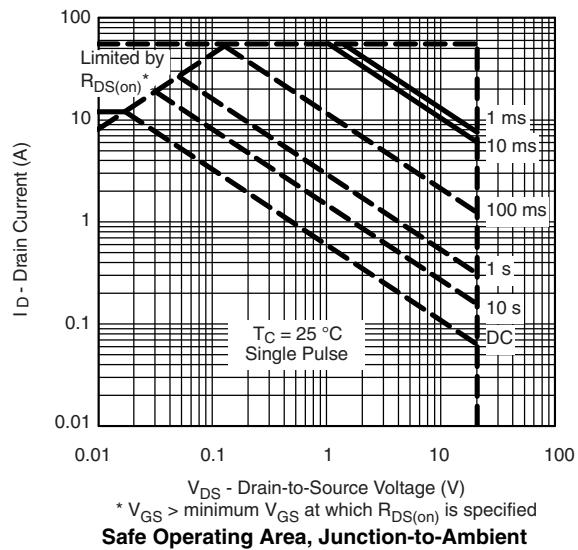
On-Resistance vs. Gate-to-Source Voltage



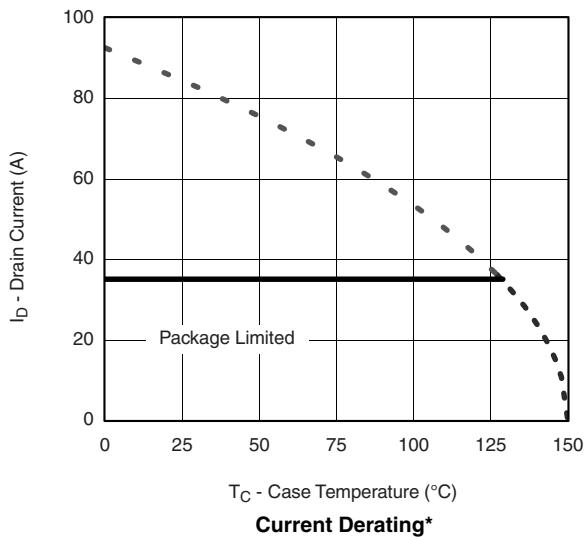
Threshold Voltage

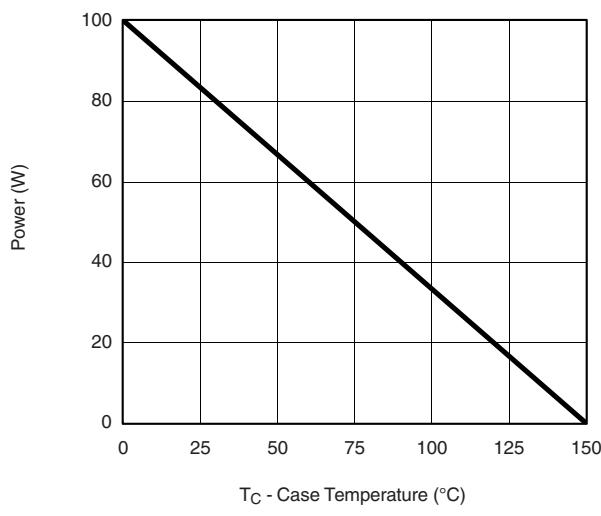


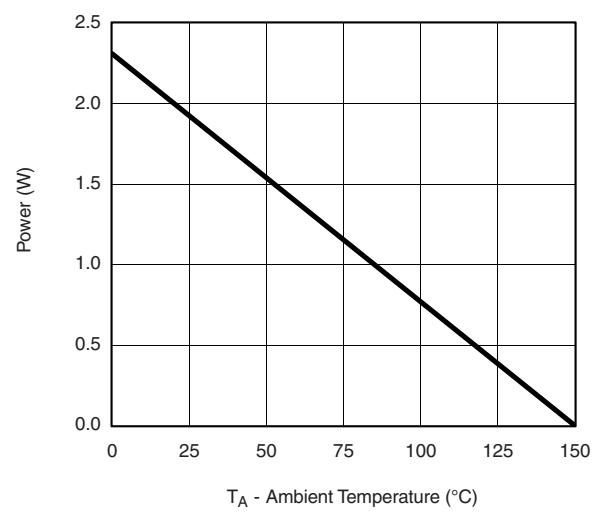
Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

 $T_C$  - Case Temperature (°C)

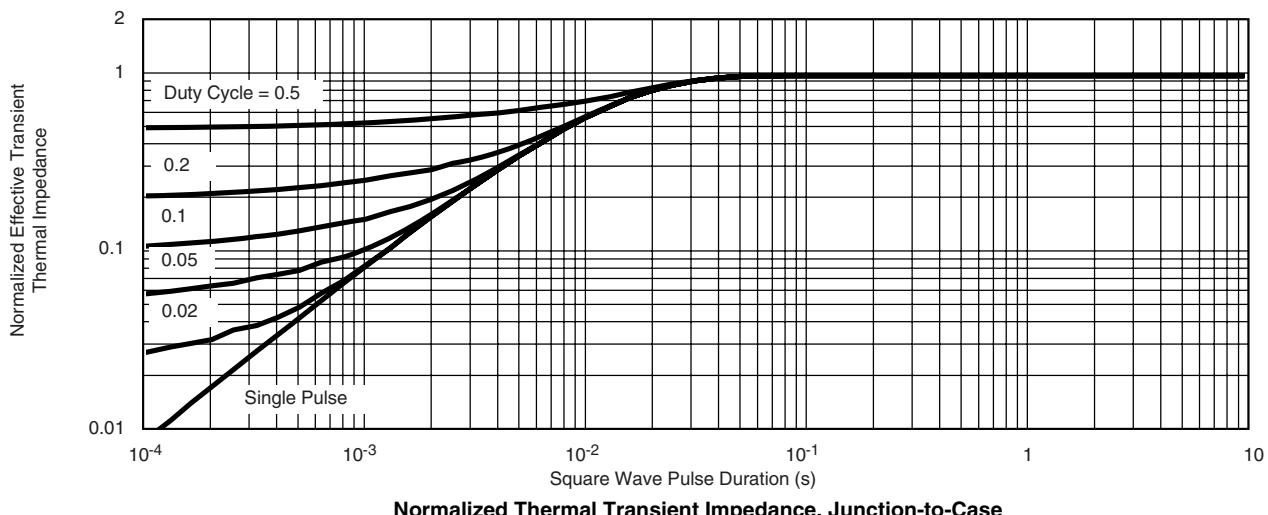
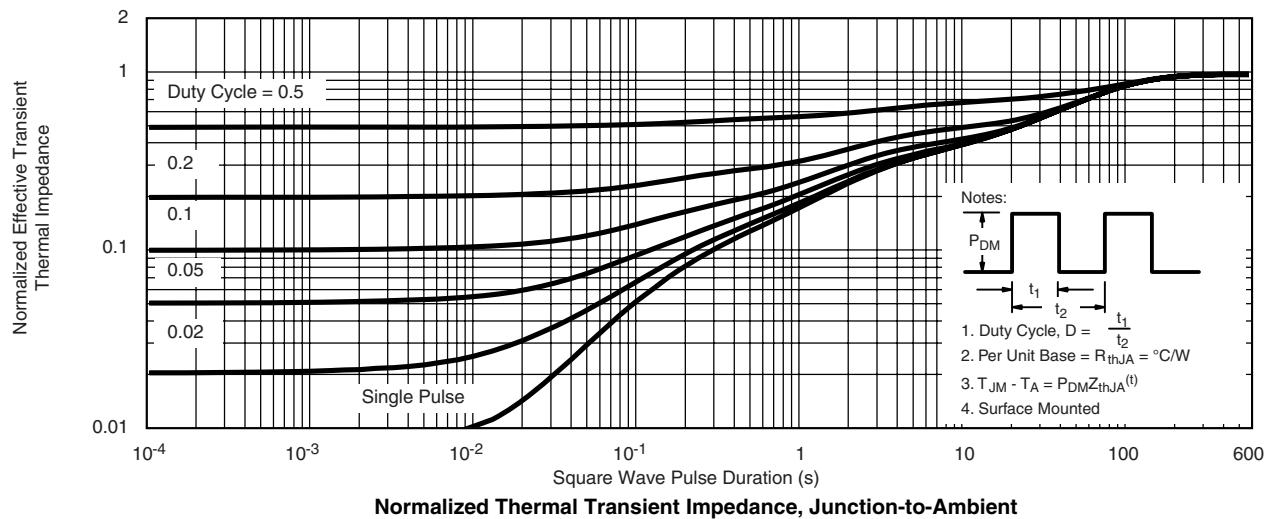
**Current Derating\***

 $T_C$  - Case Temperature (°C)

**Power, Junction-to-Case**

 $T_A$  - Ambient Temperature (°C)

**Power, Junction-to-Ambient**

\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



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